

**EPOXY PHOTORESIST COMPOSITION WITH IMPROVED CRACKING  
RESISTANCE**

**ABSTRACT OF THE DISCLOSURE**

A photoimageable composition suitable for use as a negative photoresist comprising about 75% to about 95% by weight of at least one epoxidized polyfunctional bisphenol A formaldehyde novolak resin; about 5% to about 25% by weight of at least one  
5 polyol reactive diluent; and at least one photoacid generator in an amount from about 2.5 to about 12.5 parts per hundred parts of resin and reactive diluent, which initiates polymerization upon exposure to near-ultraviolet radiation; dissolved in a sufficient amount of coating solvent.

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